# ACCELERATE®HD HIGH-DENSITY SLIM BODY ARRAYS (0.635 mm) .025" PITCH

### **FEATURES & BENEFITS**

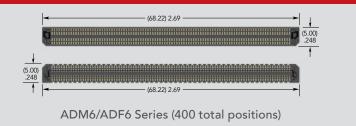
- Up to 240 positions in 4-row design (400 positions in development)
- Low-profile 5 mm stack heights
- Slim 5 mm width body design
- Edge Rate<sup>®</sup> contact system optimized for signal integrity performance
- Open-pin-field for grounding and routing flexibility
- PCIe<sup>®</sup> 5.0 capable
- Compatible with mPower<sup>®</sup> (UMPT/UMPS) for a power signal solution





Solder ball technology for simplified processing

#### HIGHER DENSITY THAN PREVIOUS GENERATION STRIPS



#### **KEY SPECIFICATIONS**

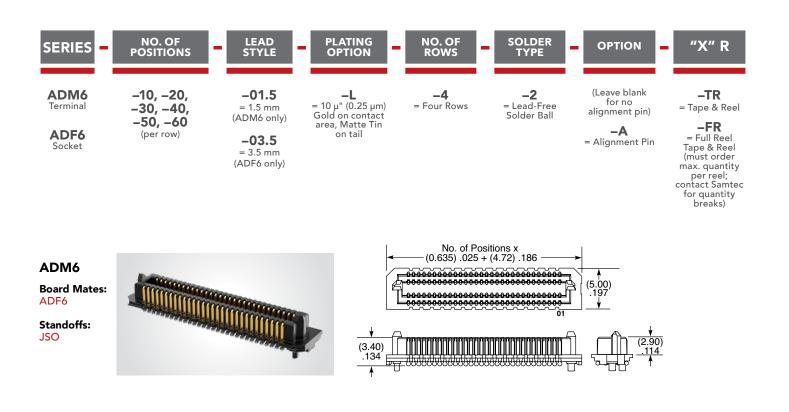
РІТСН	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
(0.635 mm) .025"	40 - 240	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 ℃ to +125 ℃	1.34 A per pin (4 pins powered)	Testing now	Yes

#### samtec.com/AcceleRateHD

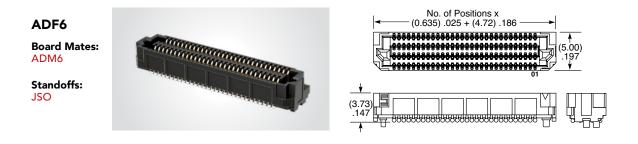
Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.



#### (0.635 mm) .025" PITCH • SLIM BODY OPEN-PIN-FIELD ARRAYS



	MATED HEIGHTS *		
	ADF6	ADM6 LEAD STYLE	
View complete specifications at: samtec.com?ADM6	LEAD STYLE	-01.5	
	-03.5	(5 mm) .197"	
	* Processing cond	ditions will affect mated height.	



**Notes:** Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?ADF6 samtec.com/AcceleRateHD

F-221 (Rev 14SEP21)

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## **Mouser Electronics**

Authorized Distributor

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Samtec: ADF6-30-03.5-L-4-2-A-TR